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|-------------------|--|
| customer | |
| pcb name | |
| WE article number | |
| engineer | |
| date | |



Multilayer 6 Layers

PCB Thickness : 1,60 mm +/- 10%

| Rigid area Structure | Rigid area Thickness | Material description | Viatypes | Layer usage | Impedance | |
|----------------------|----------------------|----------------------|--------------|-------------|-----------|------------------------|
| | | | | | Er | Z[Ohm] Line / Space |
| Soldermask | 15 | | | | | |
| L1 | 45 | * Incl. Plating | Top-Layer | | 3,5 | |
| | 230 | FR4 TG 135 | | | 3,9 | |
| L2 | 18 | | | | | |
| | 360 | FR4 TG 135 | | | 4,1 | |
| L3 | 18 | | | | | |
| | 230 | FR4 TG 135 | | | 3,9 | |
| L4 | 18 | | | | | |
| | 360 | FR4 TG 135 | | | 4,1 | |
| L5 | 18 | | | | | |
| | 230 | FR4 TG 135 | | | 3,9 | |
| L6 | 45 | * Incl. Plating | Bottom-Layer | | | |
| Soldermask | 15 | | | | 3,5 | |

Notes:

50 % copper occupancy IL

final copper thickness according to IPC 6012

Dielectric material according IPC-4101 E / 24

For Microvia technology please use our HDI stackups

Revision: Created: W. Brylka / Scrutinised: A. Schilpp / Approved: A.Schilpp

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Via types - Standard and options

